

DF005S THRU DF10S

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DF005S THRU DF10S

1.0A Miniature Glass Passivated Single-Phase Surface Mount Bridge Rectifiers 50-1000V

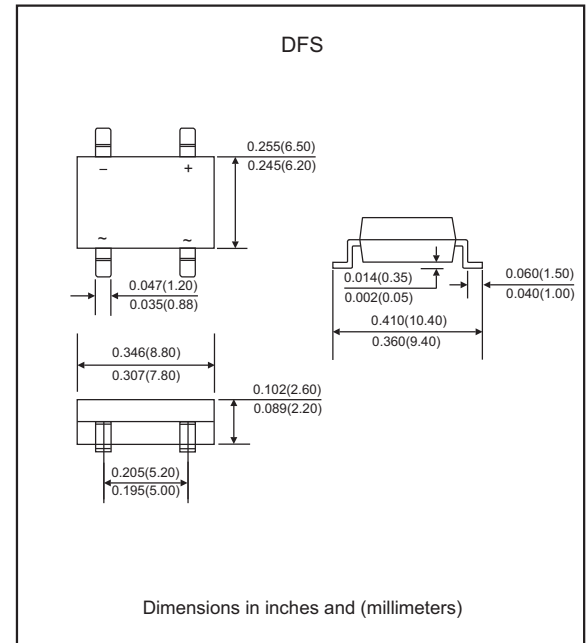
Features

- Surge overload ratings to 30 amperes peak
- Surface mount type for automated replacement
- Ideal for printed board
- Low forward drop down voltage
- Reliable low cost construction utilizing molded plastic technology results in inexpensive product
- Glass passivated chip junctions
- Lead-free parts meet RoHS requirements
- UL recognized file # E321971
- Suffix "-H" indicates Halogen free parts, ex. DF005S-H

Mechanical data

- Epoxy:UL94-V0 rated flame retardant
- Case : Molded plastic, DFS
- Terminals : Solder plated, solderable per MIL-STD-750, Method 2026
- Polarity : marked on body
- Mounting Position : Any
- Weight : Approximated 0.34 gram

Package outline



Maximum ratings and Electrical characteristics (AT $T_A=25^{\circ}\text{C}$ unless otherwise noted)

PARAMETER	CONDITIONS	Symbol	MIN.	TYP.	MAX.	UNIT
Forward rectified current	See Fig.1	I_O			1.0	A
Forward surge current	8.3ms single half sine-wave (JEDEC methode)	I_{FSM}			30	A
Reverse current per element	$V_R = V_{RRM} \quad T_J = 25^{\circ}\text{C}$	I_R			10	μA
	$V_R = V_{RRM} \quad T_J = 125^{\circ}\text{C}$				500	
I^2t Rating for Fusing	$t < 8.3\text{ms}$	I^2t			3.74	A^2s
Typical junction capacitance Per element	Measured at 1.0MHz and applied reverse voltage of 4.0V DC	C_J		25		pF
Typical thermal resistance	Junction to ambient mounted on P.C.B with 0.5*0.5"(13*13mm) copper pads.	$R_{\theta JA}$		40		$^{\circ}\text{C/W}$
Storage temperature		T_{STG}	-65		+175	$^{\circ}\text{C}$

SYMBOLS	V_{RRM}^{*1} (V)	V_{RMS}^{*2} (V)	V_R^{*3} (V)	V_F^{*4} (V)	Operating temperature $T_J, (^{\circ}\text{C})$
DF005S	50	35	50	1.10	-55 to +150
DF01S	100	70	100		
DF02S	200	140	200		
DF04S	400	280	400		
DF06S	600	420	600		
DF08S	800	560	800		
DF10S	1000	700	1000		

*1 Repetitive peak reverse voltage

*2 RMS voltage

*3 Continuous reverse voltage

*4 Maximum forward voltage per element@ $I_F=1.0\text{A}$

Rating and characteristic curves (DF005S THRU DF10S)

FIG.1-FORWARD CURRENT DERATING CURVE

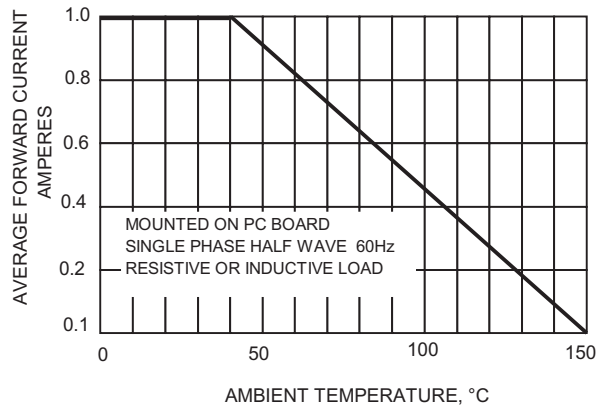


FIG.2-MXIMUM NON-REPETITIVE SURGE CURRENT

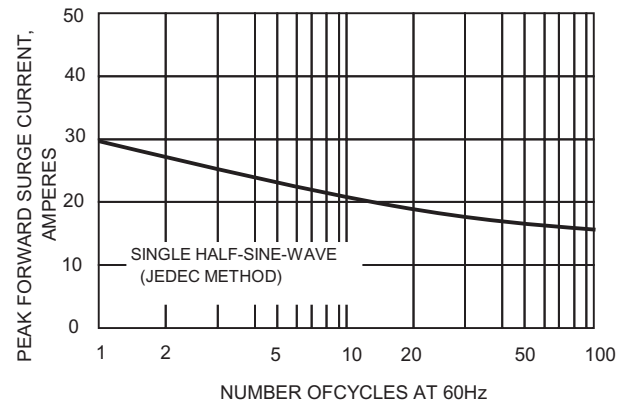


FIG.3-TYPICAL JUNCTION CAPACITANCE

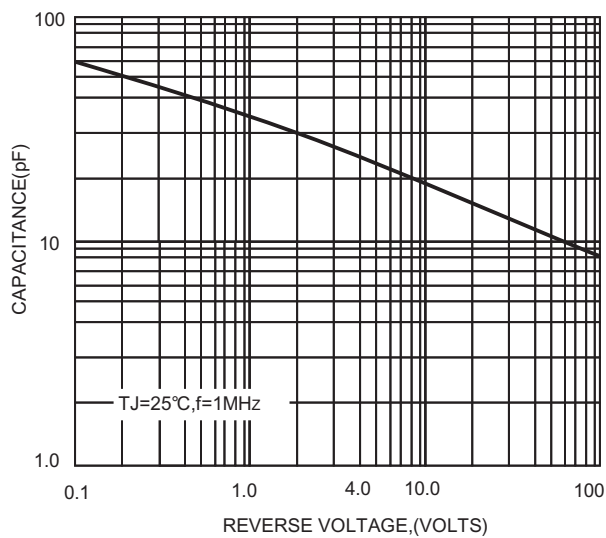


FIG.4-TYPICAL FORWARD CHARACTERISTICS

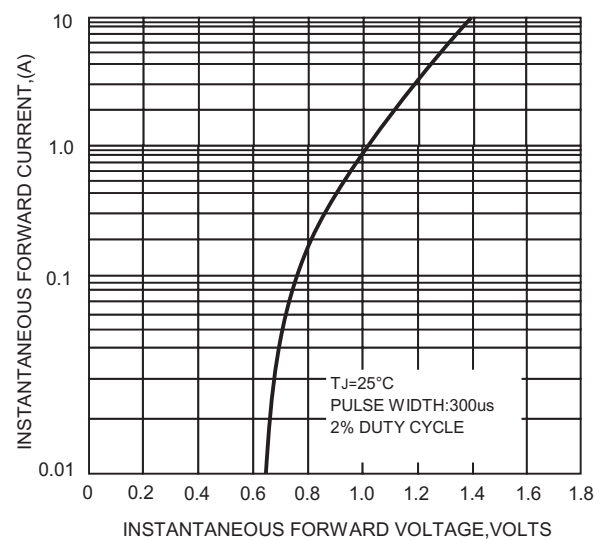
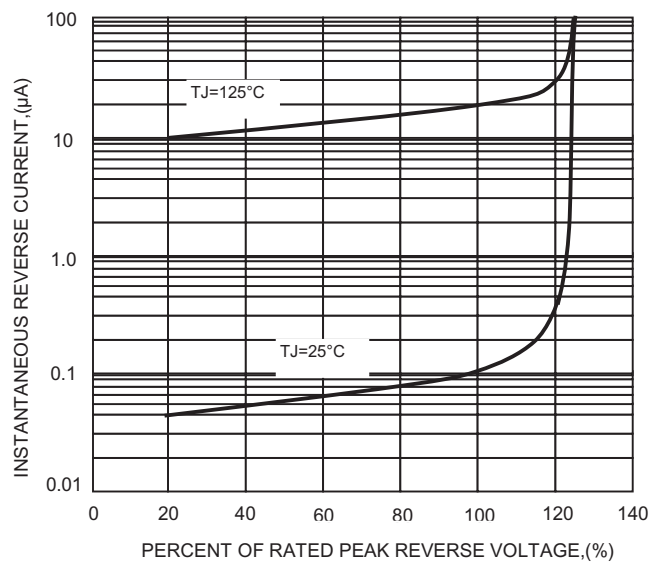
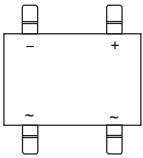
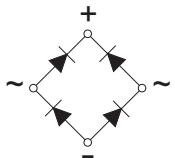


FIG.5-TYPICAL REVERSE CHARACTERISTICS



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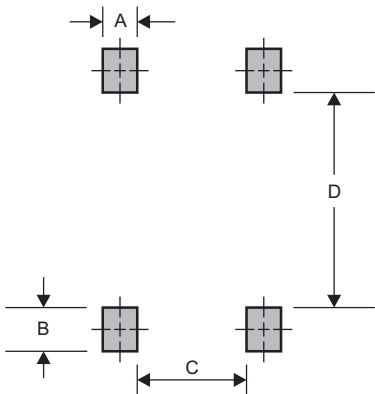
Pinning information

Simplified outline	Symbol
	

Marking

Type number	Marking code
DF005S	DF005S
DF01S	DF01S
DF02S	DF02S
DF04S	DF04S
DF06S	DF06S
DF08S	DF08S
DF10S	DF10S

Suggested solder pad layout

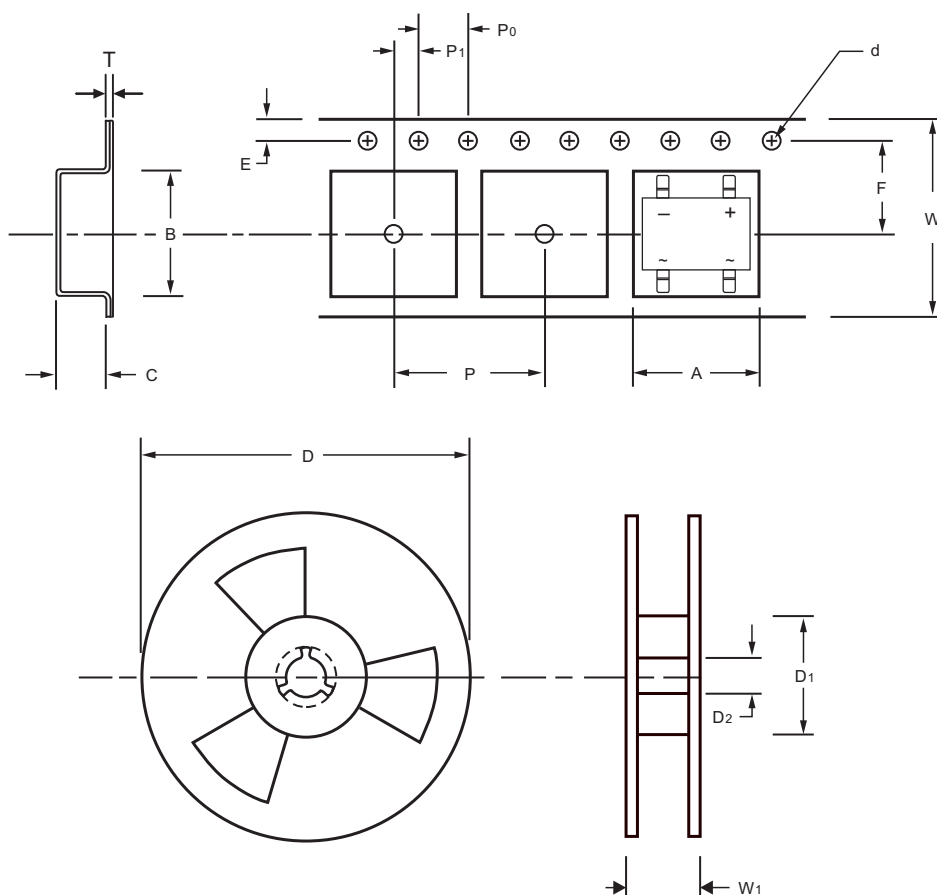


Dimensions in inches and (millimeters)

PACKAGE	A	B	C	D
DFS	0.059 (1.50)	0.047 (1.20)	0.157 (4.00)	0.291 (7.40)

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Packing information



unit:mm

Item	Symbol	Tolerance	DFS
Carrier width	A	0.1	8.64
Carrier length	B	0.1	10.41
Carrier depth	C	0.1	3.50
Sprocket hole	d	0.1	1.50
13" Reel outside diameter	D	2.0	330.00
13" Reel inner diameter	D1	min	50.00
7" Reel outside diameter	D	2.0	-
7" Reel inner diameter	D1	min	-
Feed hole diameter	D2	0.5	13.00
Sprocket hole position	E	0.1	1.75
Punch hole position	F	0.1	7.50
Punch hole pitch	P	0.1	12.00
Sprocket hole pitch	P0	0.1	4.00
Embossment center	P1	0.1	2.00
Overall tape thickness	T	0.1	0.30
Tape width	W	0.3	16.00
Reel width	W1	1.0	22.00

Note: Devices are packed in accordance with EIA standard RS-481-A and specifications listed above.

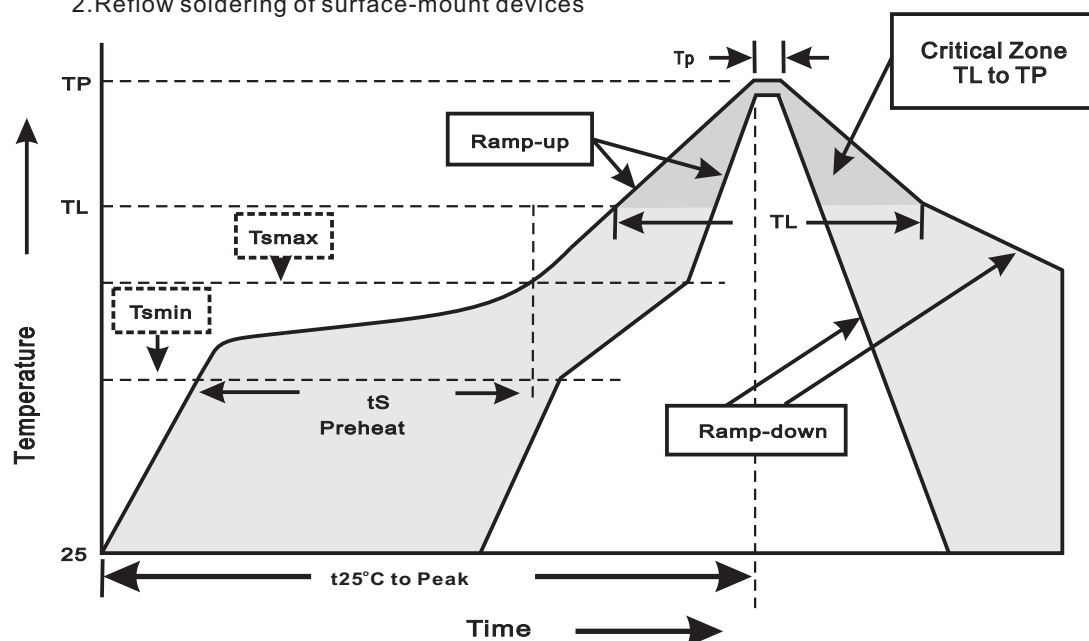
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Reel packing

PACKAGE	REEL SIZE	REEL (pcs)	COMPONENT SPACING (m/m)	BOX (pcs)	INNER BOX (m/m)	REEL DIA. (m/m)	CARTON SIZE (m/m)	CARTON (pcs)	APPROX. GROSS WEIGHT (kg)
DFS	13"	1,500	12.0	3,000	335*335*38	330	350*330*360	12,000	11.0

Suggested thermal profiles for soldering processes

- 1.Storage environment: Temperature=5°C~40°C Humidity=55%±25%
- 2.Reflow soldering of surface-mount devices



3.Reflow soldering

Profile Feature	Soldering Condition
Average ramp-up rate(T _L to T _P)	<3°C/sec
Preheat -Temperature Min(T _{Smin}) -Temperature Max(T _{Smax}) -Time(min to max)(t _S)	150°C 200°C 60~120sec
T _{Smax} to T _L -Ramp-upRate	<3°C/sec
Time maintained above: -Temperature(T _L) -Time(t _L)	217°C 60~260sec
Peak Temperature(T _P)	255°C-0/+5°C
Time within 5°C of actual Peak Temperature(t _P)	10~30sec
Ramp-down Rate	<6°C/sec
Time 25°C to Peak Temperature	<6minutes

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High reliability test capabilities

Item Test	Conditions	Reference
1. Solder Resistance	at $260 \pm 5^{\circ}\text{C}$ for $10 \pm 2\text{sec.}$	MIL-STD-750D METHOD-2031
2. Solderability	at $245 \pm 5^{\circ}\text{C}$ for 5 sec.	MIL-STD-202F METHOD-208
3. High Temperature Reverse Bias	$V_R = 80\%$ rate at $T_J = 150^{\circ}\text{C}$ for 168 hrs.	MIL-STD-750D METHOD-1038
4. Forward Operation Life	Rated average rectifier current at $T_A = 25^{\circ}\text{C}$ for 500hrs.	MIL-STD-750D METHOD-1027
5. Intermittent Operation Life	$T_A = 25^{\circ}\text{C}$, $I_F = I_O$ On state: power on for 5 min. off state: power off for 5 min. on and off for 500 cycles.	MIL-STD-750D METHOD-1036
6. Pressure Cooker	$15P_{SIG}$ at $T_A = 121^{\circ}\text{C}$ for 4 hrs.	JESD22-A102
7. Temperature Cycling	-55°C to $+125^{\circ}\text{C}$ dwelled for 30 min. and transferred for 5min. total 10 cycles.	MIL-STD-750D METHOD-1051
9. Forward Surge	8.3ms single half sine-wave , one surge.	MIL-STD-750D METHOD-4066-2
10. Humidity	at $T_A = 85^{\circ}\text{C}$, RH=85% for 1000hrs.	MIL-STD-750D METHOD-1021
11. High Temperature Storage Life	at 175°C for 1000 hrs.	MIL-STD-750D METHOD-1031